PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT8077807

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HSIN-WEN SU	06/19/2019
YU-KUAN LIN	06/19/2019
CHIH-CHUAN YANG	06/19/2019
CHANG-TA YANG	06/23/2019
SHIH-HAO LIN	06/19/2019

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	8, LI-HSIN RD. 6
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18359034

CORRESPONDENCE DATA

Fax Number: (214)200-0853

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: IPDOCKETING@HAYNESBOONE.COM
Correspondent Name: HAYNES AND BOONE, LLP
Address Line 1: 2323 VICTORY AVENUE
Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:	2018-3076/24061.3871US03
NAME OF SUBMITTER:	KENNEDY A. BROWN
SIGNATURE:	/Kennedy A. Brown/
DATE SIGNED:	07/26/2023

Total Attachments: 4
source=24061.3871US03 - Assignment [parent]#page1.tif

source=24061.3871US03 - Assignment [parent]#page2.tif
source=24061.3871US03 - Assignment [parent]#page3.tif
source=24061.3871US03 - Assignment [parent]#page4.tif

ASSIGNMENT

WHEREAS, we,

(1)	Hsin-Wen Su	of	Hsinchu, Taiwan, Republic of China
(2)	Yu-Kuan Lin	of	Taipei City, Taiwan, Republic of China
(3)	Chih-Chuan Yang	of	Hsinchu, Taiwan, Republic of China
(4)	Chang-Ta Yang	of	Hsinchu City, Taiwan, Republic of China
(5)	Shih-Hao Lin	of	Hsinchu, Taiwan, Republic of China

have invented certain improvements in

CUT METAL GATE IN MEMORY MACRO EDGE AND MIDDLE STRAP

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
_X_ filed on 06-14-2019 and assigned application number 16/441,217 ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Hsin-Wen Su

Residence Address: 8, Li-Hsin Rd. 6
Hsinchu, Taiwan 300-78, Republic of China

Dated: 2019/6/19

Hsin-Wen Su
Inventor Signature

Inventor Name: Yu-Kuan Lin

Residence Address: 5F, No. 24, Ln. 26, TaiShun St., Daan District
Taipei City, Taiwan, Republic of China

Dated: 2019/6/19

Yu Kuan Lin
Inventor Signature

Inventor Name: Chih-Chuan Yang

Residence Address: 8, Li-Hsin Rd. 6
Hsinchu, Taiwan 300-78, Republic of China

Dated: 2019/6/19

Chih-Chuan Yang
Inventor Signature

Inventor Name: Chang-Ta Yang

Residence Address: No. 28, Ln. 443, Minghu Rd., East Dist.
Hsinchu City 300, Taiwan, Republic of China

Dated: 2019/6/23

Chang-Ta Yang
Inventor Signature

Inventor Name: Shih-Hao Lin

Residence Address: 8, Li-Hsin Rd. 6
Hsinchu, Taiwan 300-78, Republic of China

Dated: _____

_____
Inventor Signature

PATENT
REEL: 064384 FRAME: 0512

Inventor Name: Chang-Ta Yang

Residence Address: No. 28, Ln. 443, Minghu Rd., East Dist.
Hsinchu City 300, Taiwan, Republic of China

Dated: _____ _____
Inventor Signature

Inventor Name: Shih-Hao Lin

Residence Address: 8, Li-Hsin Rd. 6
Hsinchu, Taiwan 300-78, Republic of China

Dated: 2019/06/19 Shih-Hao Lin
Inventor Signature